

Abstract

The present invention provides a cleaning agent for removing the solder flux and method for cleaning the solder flux which exhibit the excellent cleaning property even at the time of cleaning a lead-free soldering flux, a high-melting-point solder flux or the like and, at the same time, exhibits the excellent rinsing property in the rinsing using an alcoholic solvent in a next step. Accordingly, the present invention provides a cleaning agent for removing the solder flux which sets a content of benzyl alcohol to a value which falls within a range of 70 to 99.9 weight% and a content of amino alcohol to a value which falls within a range of 0.1 to 30 weight% when a content of a glycol compound is below 1 weight% with respect to a total amount of the cleaning agent for removing the solder flux, and sets a content of benzyl alcohol to a value which falls within a range of 15 to 99 weight% and a content of amino alcohol to a value which falls within a range of 0.1 to 30 weight% when a content of the glycol compound falls within a range of 1 to 40 weight% with respect to a total amount of the cleaning agent for removing the solder flux. The cleaning agent for removing the solder flux is used for cleaning the lead-free solder flux and the high-melting-point solder flux or the like.